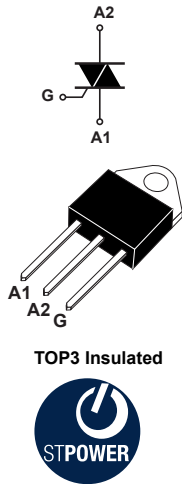


**50 A - 800 V - 150 °C 8H - Triac in TOP3 Ins.**

**Features**

- 50 A RMS Snubberless Triac
- 800 V symmetrical blocking voltage
- 150 °C maximum junction temperature  $T_j$
- Three triggering quadrants
- High noise immunity - static  $dV/dt$
- Robust dynamic turn-off commutation -  $(di/dt)_c$
- ECOPACK2 compliant component
- Molding resin UL94-V0 Flammability certified
- Comply with UL1557 insulation: 2.5 kV
  - Reference file: E81734

**Application**

- Home automation Smart AC plug
- Water heater, room heater and coffee machine
- AC Induction and Universal Motor control
- Inrush current limiter in AC DC rectifiers
- Lighting and automation I/O control
- General purpose AC line load control

**Product status link**
[T5035H-8PI](#)
**Product summary**

$I_{T(RMS)}$	50 A
$V_{DRM}/V_{RRM}$	800 V
$V_{DSM}/V_{RSM}$	900 V
$I_{GT}$	35 mA
$T_j \text{ max.}$	150 °C

**Description**

This 50 A Triac housed in TOP3 insulated is designed to operate at 800 V and 150 °C. The **T5035H-8PI** Triac provides an enhanced thermal management: this is the right choice for a compact drive of heavy AC loads and enables the heatsink size reduction.

Based on the latest ST high temperature Snubberless technology, it offers our highest specified turn off commutation and noise immunity levels at the  $T_j \text{ max.}$

The **T5035H-8PI** safely optimizes the control of the motors, heaters and inductive loads for the most constraining environments of industrial and home appliances.

By using an internal ceramic pad, it provides a recognized voltage insulation, rated at 2500  $V_{RMS}$ .

# 1 Characteristics

**Table 1. Absolute maximum ratings (limiting values)**

Symbol	Parameter	Value	Unit
$I_{T(RMS)}$	RMS on-state current (full sine wave)	$T_c = 107\text{ }^\circ\text{C}$	4 A
$I_{TSM}$	Non repetitive surge peak on-state current (full cycle, $T_j$ initial = $25\text{ }^\circ\text{C}$ )	$t = 16.7\text{ ms}$	16 A
		$t = 20\text{ ms}$	15
$I^2t$	$I^2t$ value for fusing	$t_p = 10\text{ ms}$	1.5 $\text{A}^2\text{s}$
$di/dt$	Critical rate of rise of on-state current, $I_G = 2 \times I_{GT}$ , $tr \leq 100\text{ ns}$ , $f = 120\text{ Hz}$	$T_j = 125\text{ }^\circ\text{C}$	50 $\text{A}/\mu\text{s}$
$V_{DRM}/V_{RRM}$	Repetitive peak off-state voltage	$T_j = 125\text{ }^\circ\text{C}$	600 V
$V_{DSM}/V_{RSM}$	Non Repetitive peak off-state voltage, 10 ms		750 V
$I_{GM}$	Maximum peak gate current	$t_p = 20\text{ }\mu\text{s}$ , $T_j = 125\text{ }^\circ\text{C}$	1.2 A
$P_{GM}$	Maximum gate power dissipation		0.5 W
$T_{stg}$	Storage temperature range		-40 to +125 $^\circ\text{C}$
$T_j$	Operating junction temperature range		-40 to +125 $^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering during 10 s		260 $^\circ\text{C}$

**Table 2. Electrical characteristics ( $T_j = 25\text{ }^\circ\text{C}$ , unless otherwise specified)**

Symbol	Test conditions	Value	Unit	
$I_{GT}^{(1)}$	$V_D = 12\text{ V}$ , $R_L = 33\text{ }\Omega$	Max.	25 mA	
$V_{GT}$	$V_D = 12\text{ V}$ , $R_L = 33\text{ }\Omega$	Max.	1.3 V	
$V_{GD}$	$V_D = V_{DRM}$ , $R_L = 3.3\text{ k}\Omega$	$T_j = 125\text{ }^\circ\text{C}$ Min.	0.2 V	
$I_L$	$I_G = 1.2 \times I_{GT}$	I-III-IV	Max.	25 mA
		II	Max.	50 mA
$I_H^{(2)}$	$I_T = 500\text{ mA}$ , gate open	Max.	25 mA	
$dV/dt^{(2)}$	$V_D = 67\% V_{DRM}$ ; $V_R = 67\% V_{RRM}$ , gate open	$T_j = 110\text{ }^\circ\text{C}$ Min.	200 $\text{V}/\mu\text{s}$	
$(di/dt)_c^{(2)}$	$(di/dt)_c = 1.8\text{ A/ms}$	$T_j = 110\text{ }^\circ\text{C}$ Min.	5 $\text{A/ms}$	

1. Minimum  $I_{GT}$  is guaranteed at 5 % of maximum  $I_{GT}$ .
2. For both polarities of OUT pin referenced to COM pin.

**Table 3. Static characteristics**

Symbol	Test conditions	$T_j$	Value	Unit
$V_{TM}^{(1)}$	$I_{TM} = 5.5\text{ A}$ , $t_p = 380\text{ }\mu\text{s}$	$25\text{ }^\circ\text{C}$	Max.	2 V
$V_{TO}^{(1)}$	Threshold voltage	$125\text{ }^\circ\text{C}$	Max.	0.95 V
$R_D^{(1)}$	Dynamic resistance	$125\text{ }^\circ\text{C}$	Max.	180 $\text{m}\Omega$
$I_{DRM}/I_{RRM}$	$V_D = V_R = V_{DRM} = V_{RRM}$	$25\text{ }^\circ\text{C}$	Max.	5 $\mu\text{A}$
		$125\text{ }^\circ\text{C}$		0.5 mA

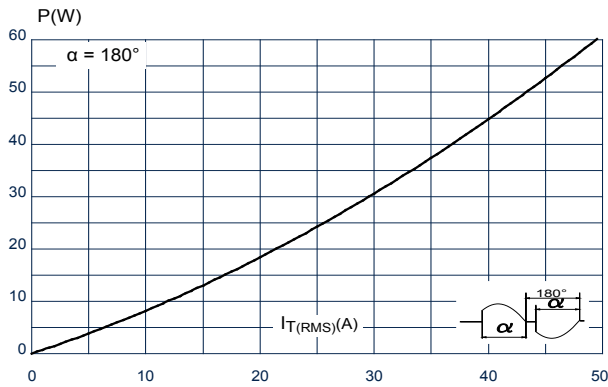
1. For both polarities of A2 referenced to A1.

**Table 4. Thermal resistance**

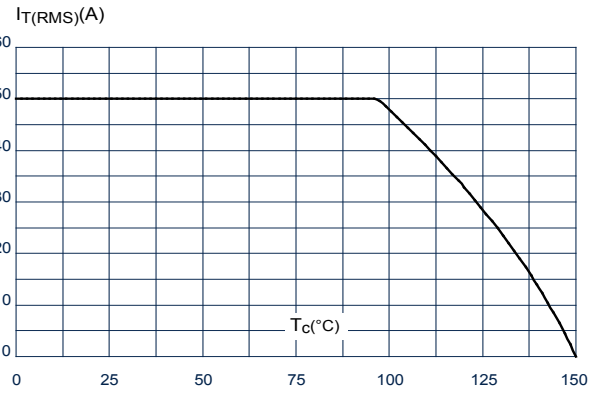
Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case (AC)	Max.	3	°C/W
$R_{th(j-a)}$	Junction to ambient: $S_{CU} = 0.5 \text{ cm}^2$	Typ.	70	°C/W

## 1.1 Characteristics (curves)

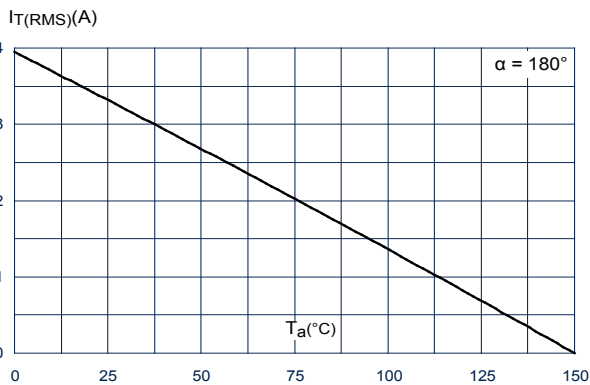
**Figure 1. Maximum power dissipation versus on-state RMS current (full cycle)**



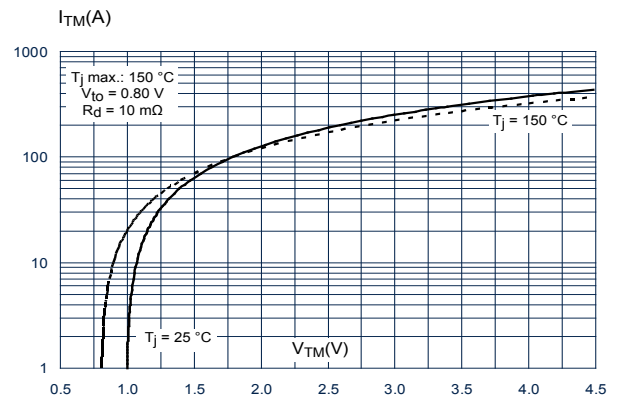
**Figure 2. On-state RMS current versus case temperature (full cycle)**



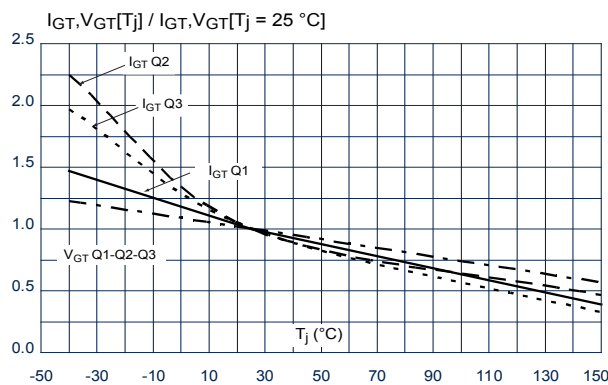
**Figure 3. On-state RMS current versus ambient temperature (free air convection)**



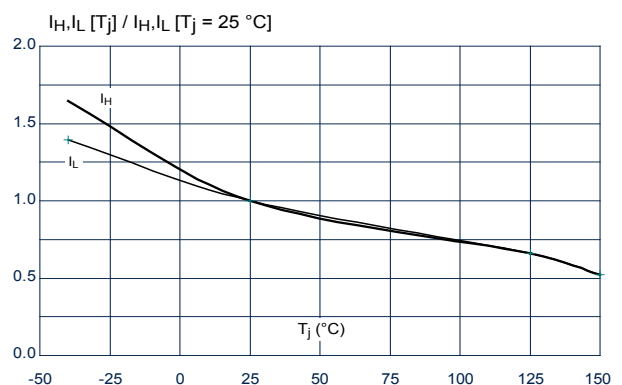
**Figure 4. On-state characteristics (maximum values)**



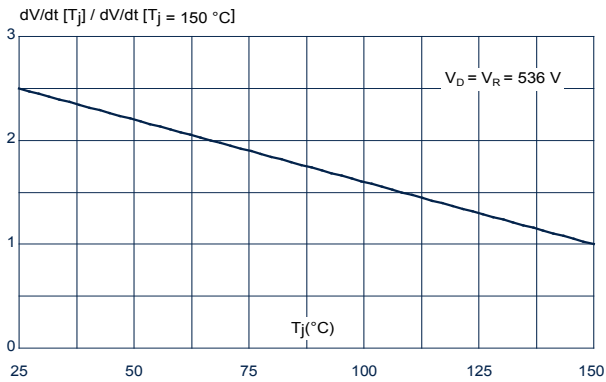
**Figure 5. Relative variation of gate triggering current and voltage versus junction temperature (typical values)**



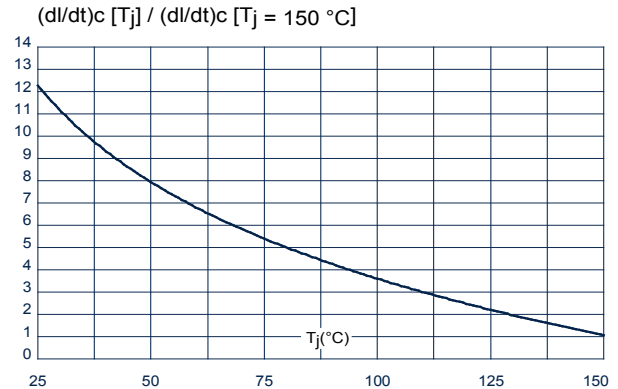
**Figure 6. Relative variation of holding current and latching current versus junction temperature (typical values)**



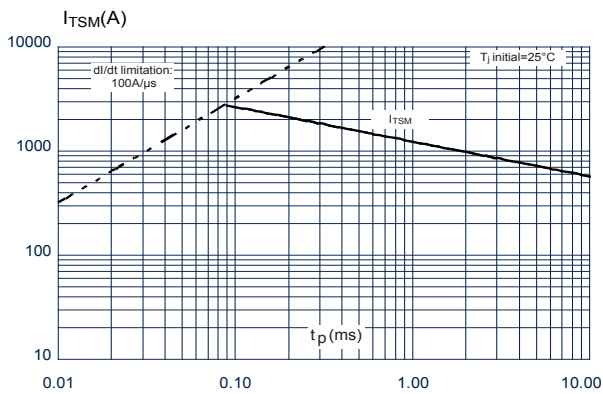
**Figure 7. Relative variation of static dV/dt immunity versus junction temperature**



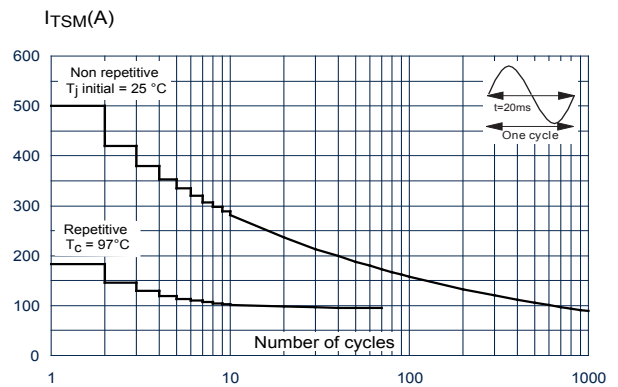
**Figure 8. Relative variation of critical rate of decrease of current (dl/dt)c versus junction temperature**



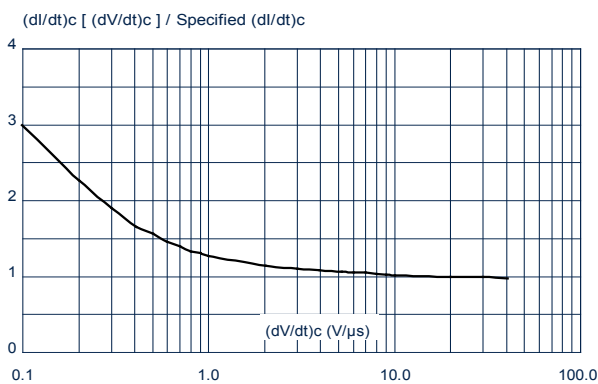
**Figure 9. Non repetitive surge peak on-state current for a sinusoidal pulse with width  $t_p < 10$  ms**



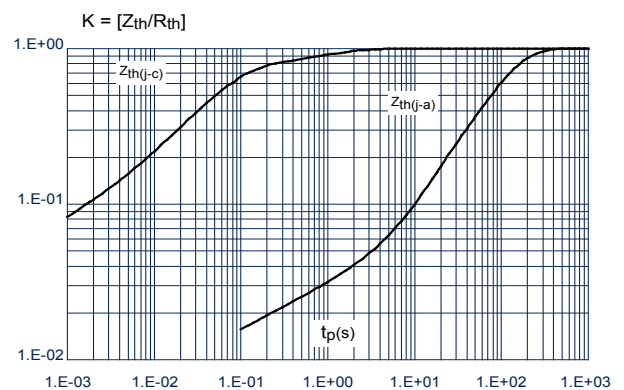
**Figure 10. Surge peak on-state current versus number of cycles**



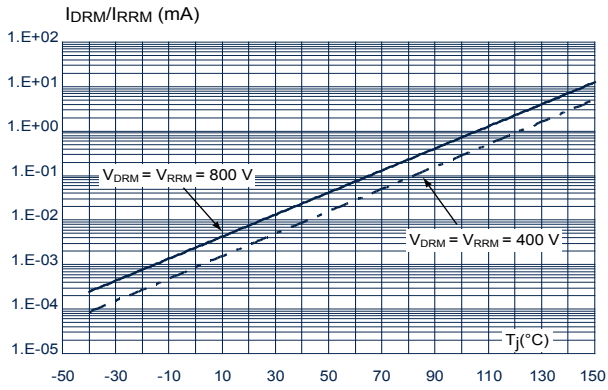
**Figure 11. Relative variation of critical rate of decrease of main current (dl/dt)c versus reapplied dV/dt (typical values)**



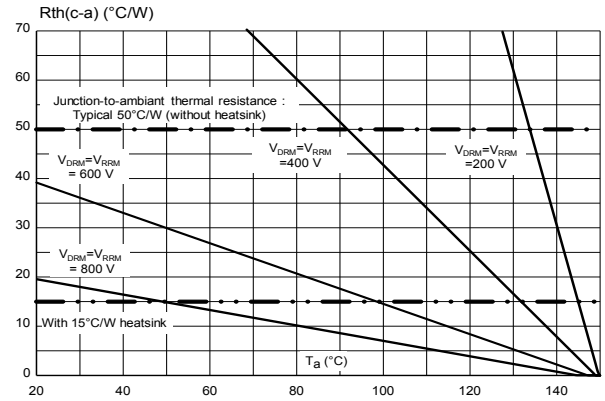
**Figure 12. Relative variation of thermal impedance versus pulse duration**



**Figure 13. Relative variation of leakage current versus junction temperature for different values of blocking voltage (typical values)**



**Figure 14. Recommended maximum case-to-ambient thermal resistance versus ambient temperature for different peak off-state voltages**



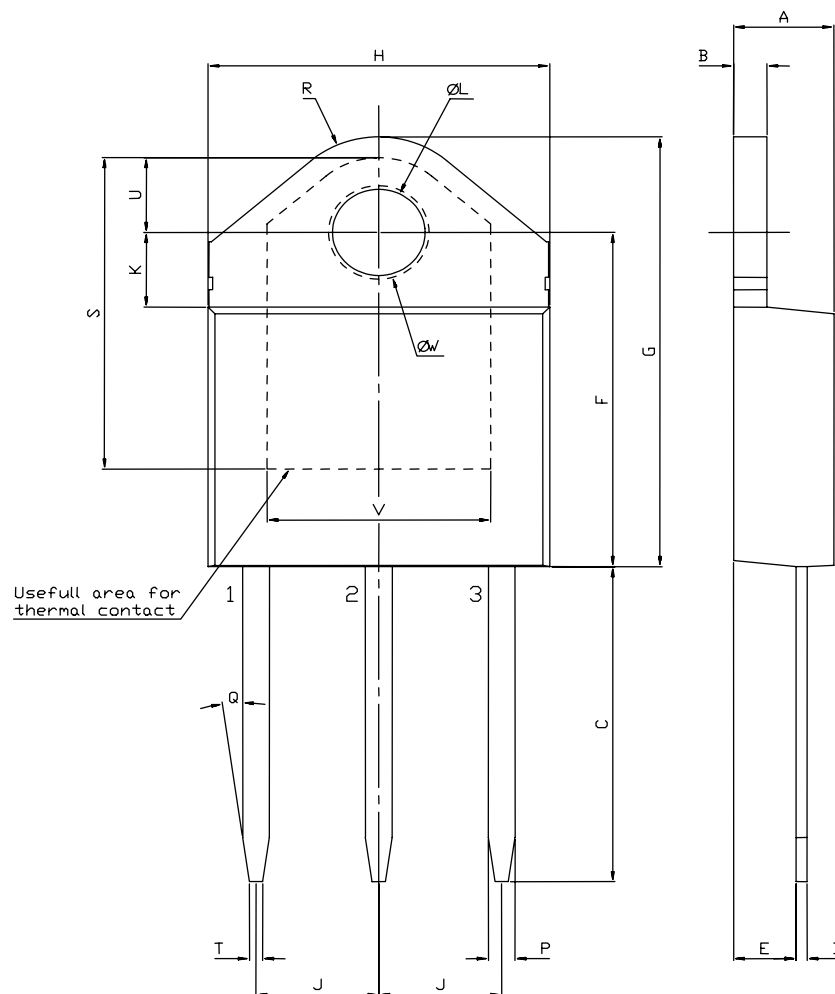
## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 2.1 TOP3 Isolated package information

- **ECOPACK** (lead-free plating and halogen free package compliance)
- Lead-free package leads finishing
- Halogen-free molding compound resin meets UL94 standard level V0
- Recommended torque: 1.05 N·m (max. torque: 1.2 N·m)

Figure 15. Package outline



**Table 5. Mechanical data**

Ref.	Dimensions					
	mm			Inches <sup>(1)</sup>		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.40		4.60	0.1732		0.1811
B	1.45		1.55	0.0571		0.0610
C	14.35		15.60	0.5650		0.6142
D	0.50		0.70	0.0197		0.0276
E	2.70		2.90	0.1063		0.1142
F	15.80		16.50	0.6220		0.6496
G	20.40		21.10	0.8031		0.8307
H	15.10		15.50	0.5945		0.6102
J	5.40		5.65	0.2126		0.2224
K	3.40		3.65	0.1339		0.1437
L	4.08		4.17	0.1606		0.1642
P	1.10		1.30	0.0430		0.0510
R		4.60			0.1811	

1. Inches given for reference only



### 3 Ordering information

Figure 16. Ordering information scheme

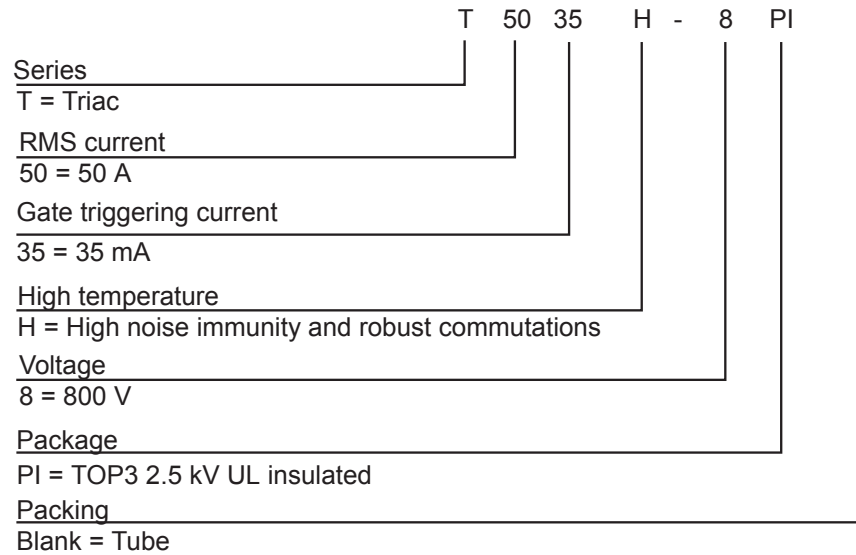


Table 6. Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
T5035H-8PI	T5035H-8PI	TOP3 Ins.	4.5 g	30	Tube

## Revision history

**Table 7. Document revision history**

Date	Revision	Changes
05-Oct-2021	1	Initial release.
27-Jul-2023	2	Updated <a href="#">Table 5</a> . Mechanical data.

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